



Material Content Data Sheet



Sales Product Name		BGA 427 H6327		Issued		19. January 2018			
MA#		MA001351532							
Package		PG-SOT343-4-1		Weight*		6.75 mg			
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]	
chip	noble metal	gold	7440-57-5	0.005	0.07		733		
	non noble metal	tin	7440-31-5	0.001	0.02		189		
	inorganic material	silicon	7440-21-3	0.037	0.54	0.63	5428	6350	
leadframe	inorganic material	silicon	7440-21-3	0.001	0.01		100		
	non noble metal	titanium	7440-32-6	0.003	0.05		498		
	non noble metal	chromium	7440-47-3	0.010	0.15		1495		
	non noble metal	copper	7440-50-8	3.347	49.63	49.84	496169	498262	
wire	noble metal	gold	7440-57-5	0.014	0.20	0.20	2032	2032	
encapsulation	organic material	carbon black	1333-86-4	0.031	0.45		4540		
	plastics	epoxy resin	-	0.658	9.76		97607		
	inorganic material	silicondioxide	60676-86-0	2.374	35.18	45.39	351838	453985	
leadfinish	non noble metal	tin	7440-31-5	0.202	2.99	2.99	29902	29902	
plating	noble metal	silver	7440-22-4	0.064	0.95	0.95	9469	9469	
*deviation	< 10%				Sum in total:		100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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